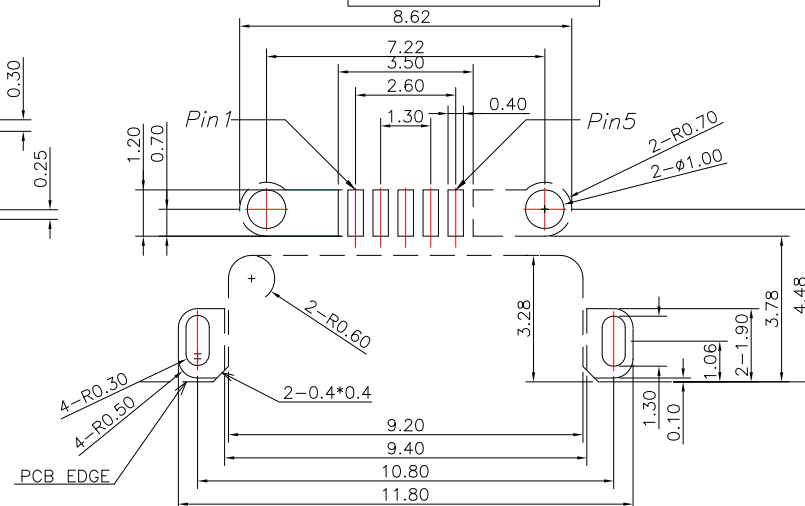
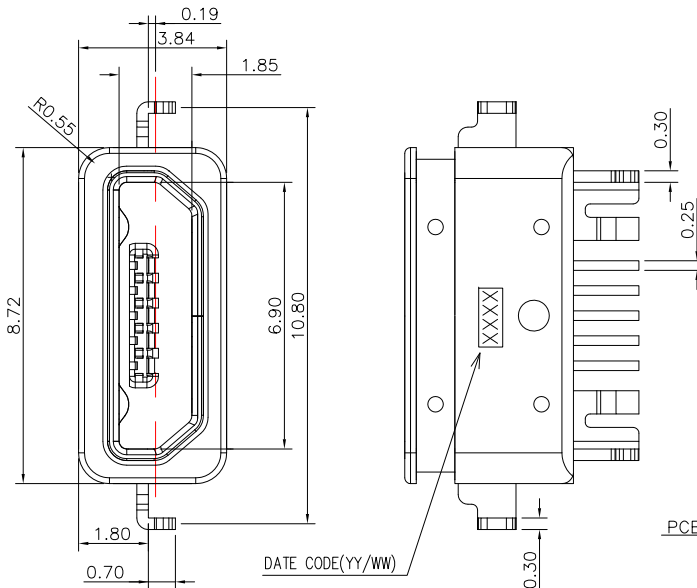
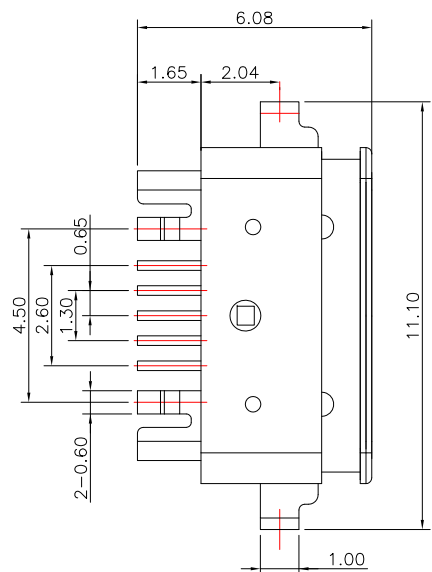
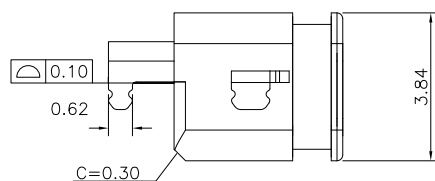


# IP67



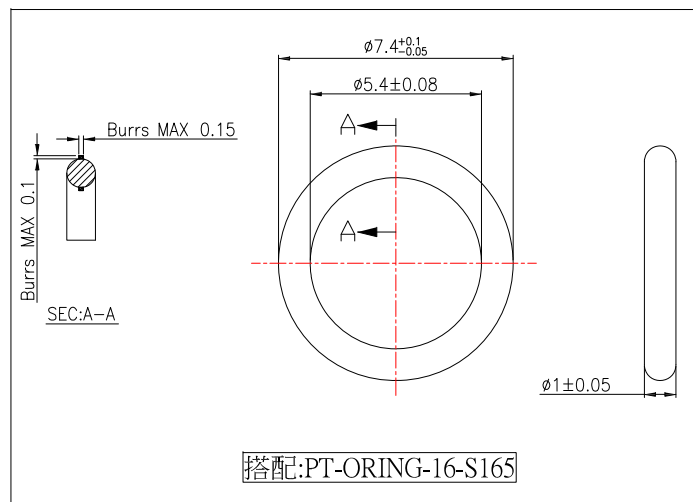
P.C.B LAYOUT MOUNTING PATTERN



MRUSB-5B-WP13-x-S165

鍍層厚度:

Blank	: 1u"
2	: 15u"
3	: 30u"



NOTES:

MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC
- 1.2 CONTACT: COPPER ALLOY
- 1.3 SHELL: SUS
- 1.4 O-RING: SILICON

FINISH:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;  
GOLD PLATED ON SOLDER BALLS ;  
NICKEL UNDER PLATED OVERALL
  - 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER
- 3.SPECIFICATION:
- 3.1 RATING: 1.0A
  - 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 500 VAC
  - 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
  - 3.4 INSULATION RESISTANCE: 1000 MΩ MIN.

5	新增O-RING圖	Jack	102920
5	刪除O-RING圖	Jack	040819
4	更新樣式	Jack	032119
3	新增O-RING圖	Jack	112618
2	新增尺寸	Jack	073118
1	更新為A0版	Jack	071718
ITEM NO.	DESCRIPTION	DRAWN	DATE

**CONTACT** 建倚科技股份有限公司  
**CONTACT TECHNOLOGY CORP.**

TOLERANCE UNLESS OTHERWISE STATED:  
 Up to 5 ±0.2  
 Above 5 ~ 15 ±0.3  
 Above 15 ~ 30 ±0.4  
 Above 30 ~ 50 ±0.5  
 Angle ±0.3°

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	10/29/20			
CHECKED BY:	DATE	FINISH	MODLE	MICRO USB 5PF B TYPE 沉板上 H 1.8 IP67
Jacky Chen	10/29/20			
APPROVED BY:	DATE	SCALE	DWG NO.	SIZE
Tony Kao	10/29/20	1 : 1		A4
		SHEET NO.	PART NO.	VER
		1 of 1	MRUSB-5B-WP13-x-S165	R6